MICROCHIP

Semiconductor Device Type: ENC-LDFN-4-5.0x3.2x1.4mm-NiAu

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Ceramic Package				43.90	100.00%	77.15%		
	Aluminum Oxide	1344-28-1	30.12		68.61%		52.93%	529285
	Silicon Oxide	14808-60-7	2.01		4.58%		3.53%	35347
	Chromium Oxide	1308-38-9	0.67		1.53%		1.18%	11780
	Molybdenum	7439-98-7	0.67		1.53%		1.18%	11811
	Cobalt	7440-48-4	0.85		1.95%		1.50%	15007
	Iron	7439-89-6	2.42		5.51%		4.25%	42511
	Nickel	7440-02-0	1.55		3.53%		2.73%	27265
	Other	Trade Secret	0.13		0.30%		0.23%	2285
	Gold	7440-57-5	0.26		0.60%		0.46%	4632
	Tungsten	7440-33-7	3.47		7.90%		6.10%	60984
	Silver	7440-22-4	1.23		2.80%		2.16%	21614
	Copper	7440-50-8	0.51		1.16%		0.90%	8955
Die				0.66	100.00%	1.16%		
	Silicon	7440-21-3	0.65		99.10%		1.15%	11459
	Aluminium	7429-90-5	0.00		0.39%		0.00%	45
	Titanium	7440-32-6	0.00		0.30%		0.00%	35
	Tungsten	7440-33-7	0.00		0.20%		0.00%	23
	Copper	7440-50-8	0.00		0.01%		0.00%	1
Die Attach 1				0.33	100.00%	0.58%		
	Silver	7440-22-4	0.24		74.00%		0.43%	4291
	Silicon Dioxide	7631-86-9	0.03		10.00%		0.06%	580
	Methanol	67-56-1	0.02		5.00%		0.03%	290
	Other	Trade Secret	0.04		11.00%		0.06%	638
Bond Wire				0.07	100.00%	0.12%		
	Gold	7440-57-5	0.07		100.00%		0.12%	1160
Blank				1.23	100.00%	2.16%		
	Silicon Dioxide	7631-86-9	1.11		90.00%		1.95%	19454
	Silver	7440-22-4	0.12		10.00%		0.22%	2162
Die Attach 2				1.41	100.00%	2.48%		
	Silver	7440-22-4	1.07		76.00%		1.88%	18832
	Epoxy Resin	Trade Secret	0.20		14.00%		0.35%	3469
	Epoxy Resin Modifier	Trade Secret	0.14		10.00%		0.25%	2478
Kovar Lid				9.31	100.00%	16.36%		
	Nickel	7440-02-0	5.03		54.00%		8.83%	88349
	Cobalt	7440-48-4	2.70		29.00%		4.74%	47447
	Iron	7439-89-6	1.58		17.00%		2.78%	27814

Totals			**56.90**	**56.90**		**100.00%**	**100.00%**	**1000000**

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